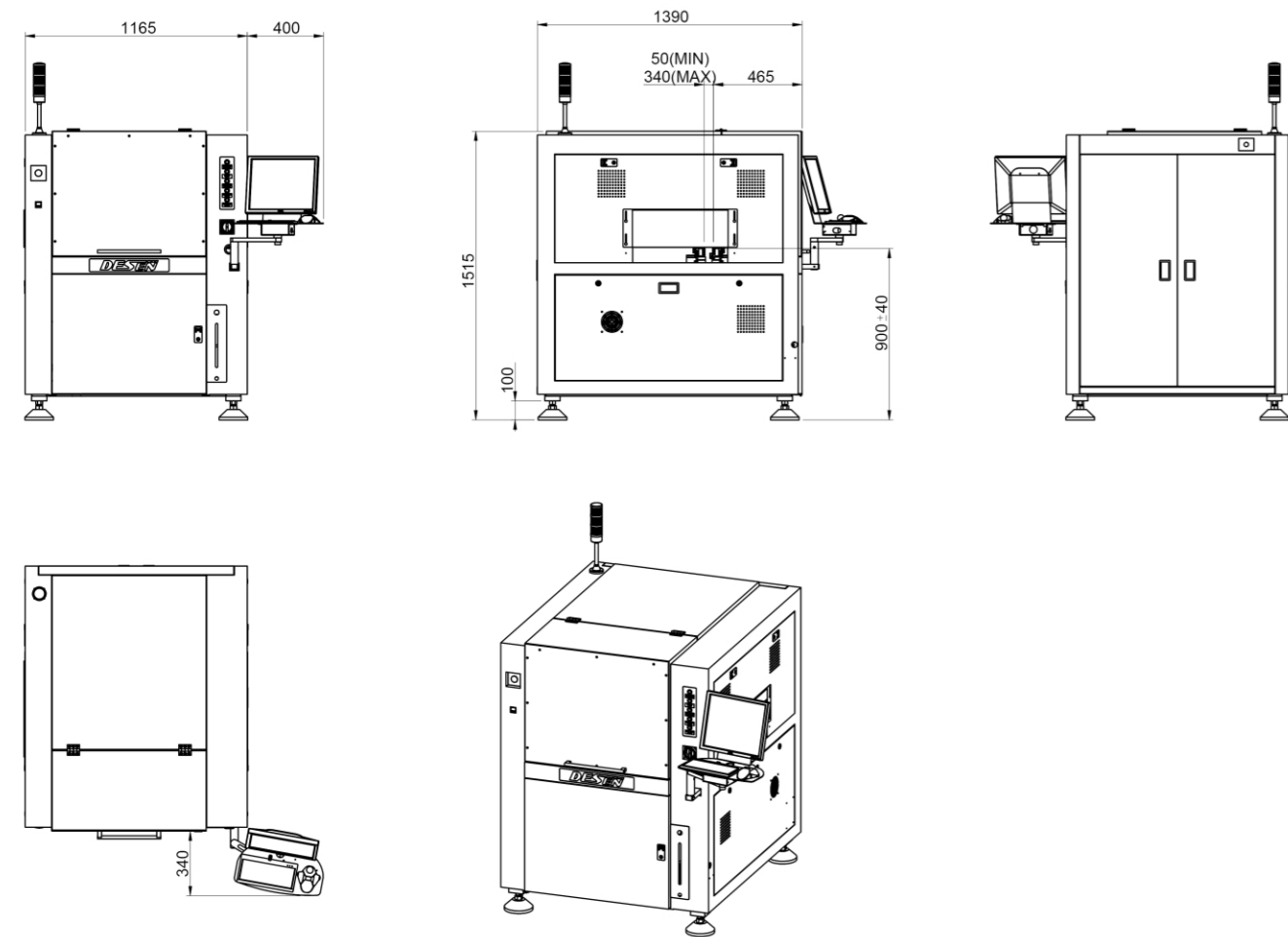
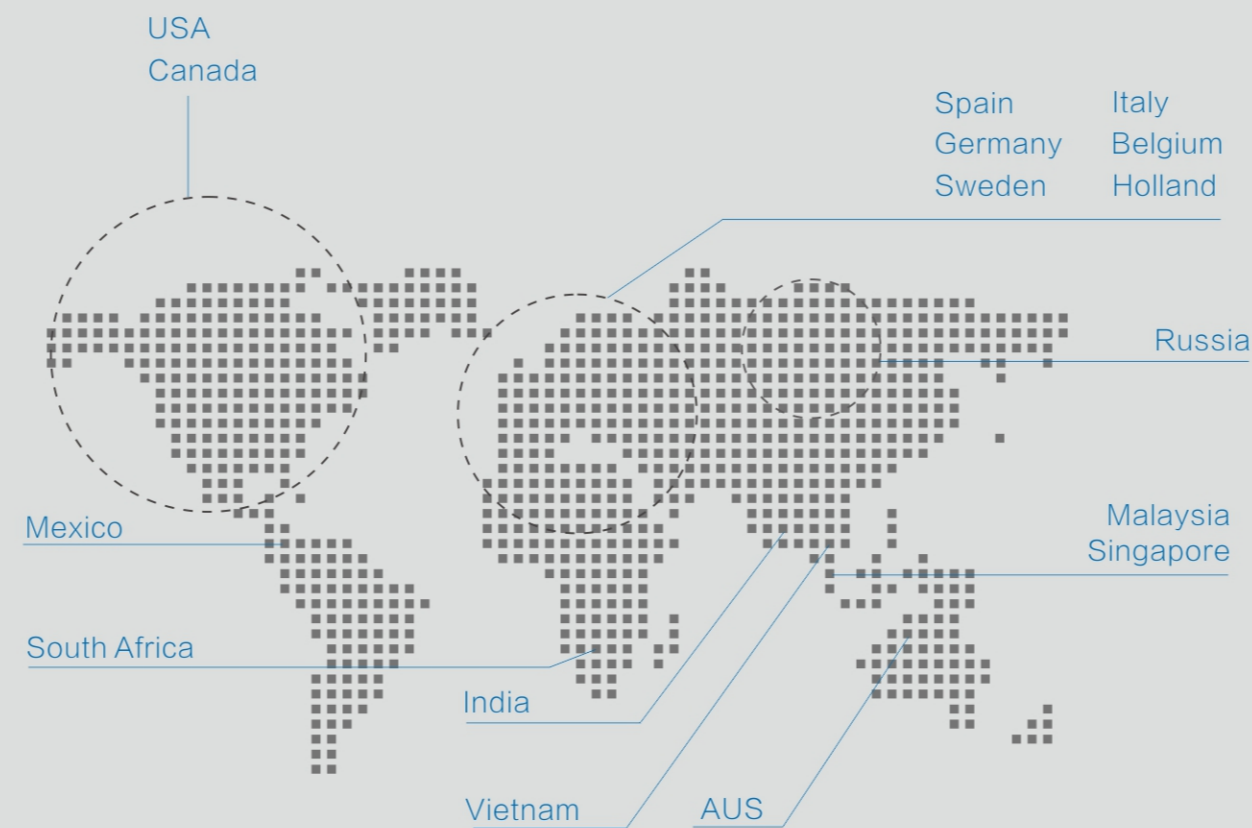
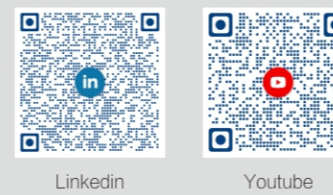


Product Size



The explanation, diagram and technical parameter are varying with continuous technology development without further notice.



Website : www.ds-smt.com
 E-mail: marketing@desen-sz.com / service@desen-sz.com
 Telephone: +86 18617023102 / +86 400 877 5520

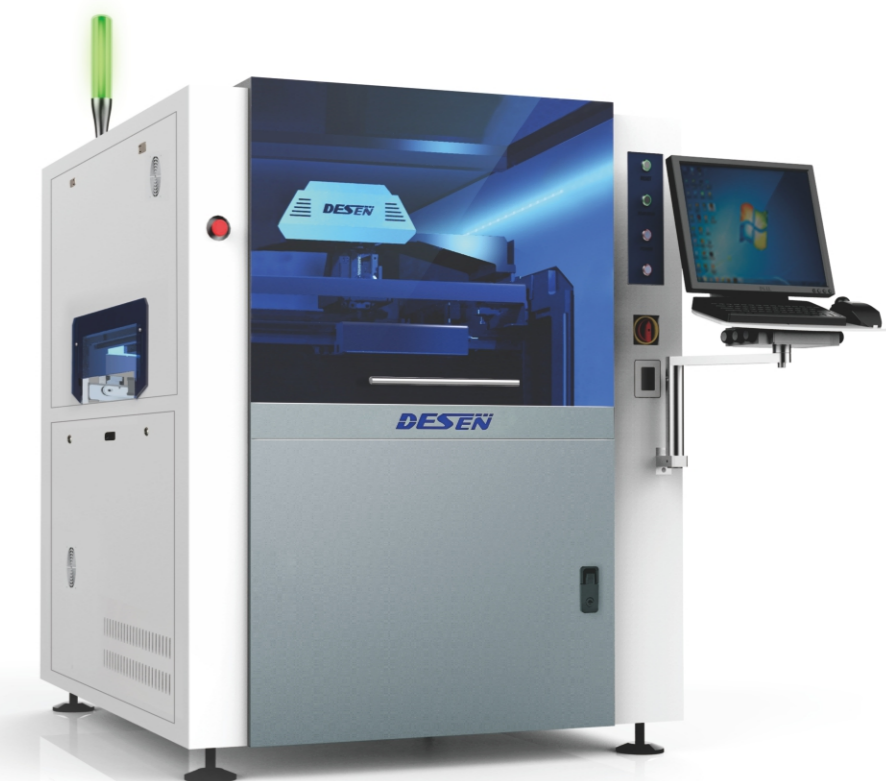
Company: Shenzhen Desen Precision Machine Co., Ltd
 Address: Building A4, The 3rd Industrial Zone in Tantou, Songgang Street, Tantou,
 Baoan District, Shenzhen City, Guangdong Province, China.



FULLY AUTOMATIC STENCIL PRINTER

DGH series

DGH



Process Parameters		Specification
⊖	Printing Accuracy	± 18 μm@6σ, Cpk≥2.0
	Repeat Position Accuracy	± 8 μm@6σ, Cpk≥2.0
		Verified by the test system CeTaQ
⏱	Cycle Time	7s
⊕	Screen Frame Size	470mm x 370mm~737mm x 737mm
⊕	Screen Frame Thickness	20mm~40mm
	Substrate Size (minimum)	50mm (X) x 50mm (Y)
⊕	Substrate Size (maximum)	400mm (X) x 340mm (Y)
	Substrate Thickness	0.4mm - 6 mm
⊕	Print Pressure	0kg~20kg
⌚	Print Speed	1 - 200mm/s
⊕	Print Gap	0mm - 20mm
	Substrate Separation	Speed:0.1 - 20mm/s Distance:0mm - 30mm
⊕	Apply Paste Option	Solder paste, printing ink, silver paste

Transportation System		Specification
⊕	Substrate Weight (maximum)	≤4kg
⏱	Transport Speed	Segmented control, 1500mm/s (Max)
⊕	Board Height	≤ 18mm (Customizable)
⊕	Transport Height	900 ± 40mm

Electrical Configuration & Environmental Requirement		Specification
⊕	Voltage	220Volts +/-10%.Single phase 50/60Hz
⊕	Power	2.5kw
⊕	Air Supply	4.5-6kgf/cm ²
⊕	Temperature	-20℃ ~ +45℃
⊕	Humidity	30% - 70% relative humidity

Standard Configuration		Specification
⊕	Stencil Alignment	Program control, Y direction positioning.
⊕	Automatic Platform Detection System	The platform height is automatically calibrated according to the thickness of the substrate.
⊕	Intelligent Transportation System	The automatic stopping device + automatic substrate positioning + left in left out, left in right out, right in right out, right in left out.
⊕	Handing & Cleaning Options	Wet cleaning + dry cleaning + vacuum (free combination)
⊕	Approximate Dimension	1165 (L) X 1390 (W) X 1515 (H) mm
⊕	Approximate Weight	1300kg packaged (depend upon configured options selected with machine)
		1100kg unpackaged (depend upon configured options selected with machine)

Product Advantages



- ⚡ Platform automatic adjustment system
- ⚡ Squeegee pressure feedback system
- ⚡ Mark camera light source automatic adjustment
- ⚡ SPI connection
- ⚡ 2D inspection
- ⚡ High-precision printing 01005, 03015

Range of Application



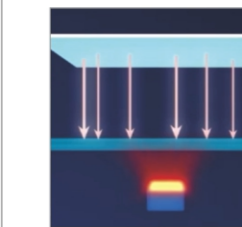
Product Advanced Options

Solder paste monitoring system



- ⚡ The sensor under the front squeegee detects the diameter of remaining solder paste and notifies customer to add solder paste.

Stencil aperture inspection system



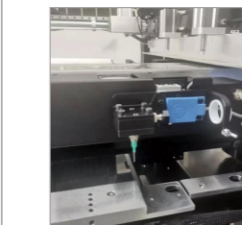
- ⚡ Judgment of aperture plugging and notify whether to clean the stencil. If the stencil inspection fails twice in a row, it will remind the customer whether to change the cleaning mode, cleaning frequency or perform manual cleaning.

Solder paste automatic adding(electric/pneumatic)



- ⚡ General solder paste pot add directly.
- ⚡ Can be added at a fixed times.

Automatic dispensing function



- ⚡ Dotted or section filling.

UPS power off protection



- ⚡ After power off in a certain time (10 minutes) PC can keep the power supply for the protection of production data.

Intelligent temperature control system



- ⚡ Temperature can be shown and adjustable on the overhead control system.
- ⚡ Temperature can be shown and adjustable on the external control system.

Industry 4.0 MES Manufacturing Execution System



- ⚡ Customized communication mode of customer to realize intelligent operation management.
- ⚡ Productivity analysis and real-time statistical operation information function.
- ⚡ Intelligent Alarm system and solutions.
- ⚡ Bar code recognition.